



SOT1425-2

WLCSP9, wafer level chip scape package, 9 terminals, 1.89 mm x 1.22 mm x 0.17 mm body

26 November 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP9
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	16-07-2013
Manufacturer package code	SOT1425-2

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.89	-	mm
package width	-	1.26	-	mm
seated height	-	0.17	-	mm
actual quantity of termination	-	9	-	



2 Package outline

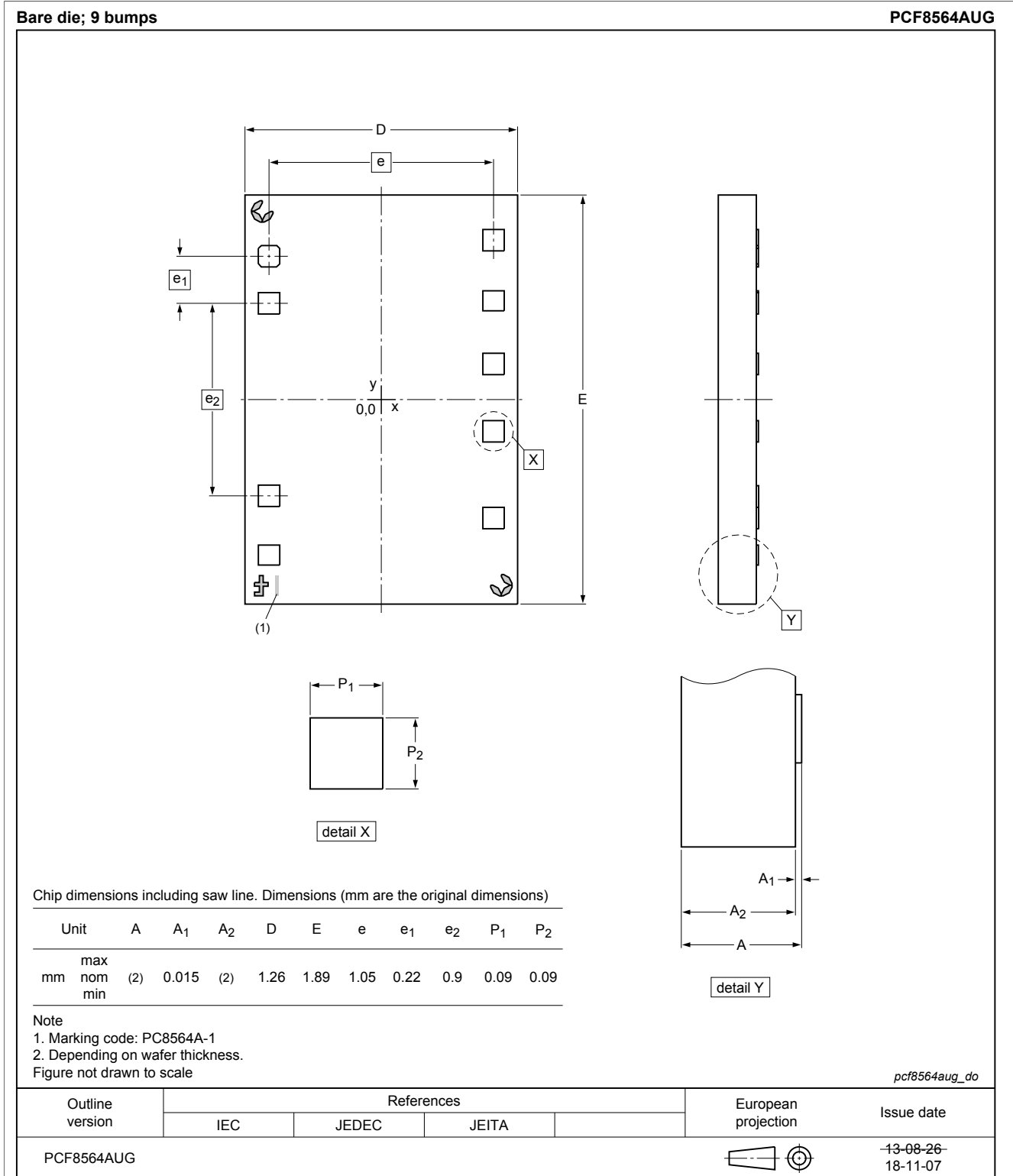


Figure 1. Package outline WLCSP9 (SOT1425-2)

3 Legal information

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